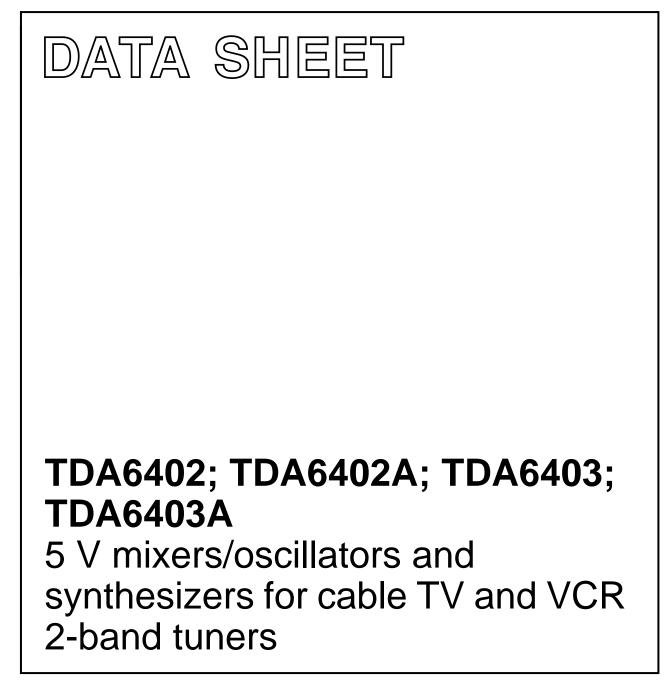
INTEGRATED CIRCUITS



Preliminary specification Supersedes data of 1996 Oct 15 File under Integrated Circuits, IC02 1997 Mar 06



TDA6402; TDA6402A;

TDA6403: TDA6403A

5 V mixers/oscillators and synthesizers for cable TV and VCR 2-band tuners

FEATURES

- Single-chip 5 V mixer/oscillator and synthesizer for cable TV and VCR tuners
- Synthesizer function compatible with existing TSA5526
- Universal bus protocol (I²C-bus or 3-wire bus)
 - bus protocol for 18 or 19-bit transmission (3-wire bus)
 - extra protocol for 27-bit transmission (test modes and features for 3-wire bus)
 - address + 4 data bytes transmission (I²C-bus 'write' mode)
 - address + 1 status byte (I²C-bus 'read' mode)
 - 4 independent I²C-bus addresses
- 1 PNP buffer for UHF band selection (25 mA)
- 3 PNP buffers for general purpose, e.g. 2 VHF sub-bands, FM sound trap (25 mA)
- 33 V tuning voltage output
- In-lock detector
- 5-step A/D converter (3 bits in I²C-bus mode)
- 15-bit programmable divider
- Programmable reference divider ratio (512, 640 or 1024)
- Programmable charge pump current (60 or 280 μA)
- Programmable automatic charge pump current switch
- · Varicap drive disable
- Mixer/oscillator function compatible with existing TDA5732
- Balanced mixer with a common emitter input for VHF (single input)
- Balanced mixer with a common base input for UHF (balanced input)
- · 2-pin common emitter oscillator for VHF
- 4-pin common emitter oscillator for UHF
- IF preamplifier with asymmetrical 75 Ω output impedance to drive a low-ohmic impedance (75 Ω)
- Low power
- · Low radiation
- Small size
- The TDA6402A and TDA6403A differ from the TDA6402 and TDA6403 by the UHF port protocol in the I²C bus mode (see Tables 3 and 4).



APPLICATIONS

- Cable tuners for TV and VCR (switched concept for VHF)
- Recommended RF bands for the USA: 55.25 to 133.25 MHz, 139.25 to 361.25 MHz and 367.25 to 801.25 MHz.

GENERAL DESCRIPTION

The TDA6402, TDA6402A, TDA6403 and TDA6403A are programmable 2-band mixers/oscillators and synthesizers intended for VHF/UHF cable tuners (see Fig.1).

The devices include two double balanced mixers and two oscillators for the VHF and UHF band respectively, an IF amplifier and a PLL synthesizer. The VHF band can be split-up into two sub-bands using a proper oscillator application and a switchable inductor. Two pins are available between the mixer output and the IF amplifier input to enable IF filtering for improved signal handling. Four PNP ports are provided. Band selection is provided by using pin PUHF. When PUHF is 'ON', the UHF mixer-oscillator is active and the VHF band is switched off. When PUHF is 'OFF', the VHF mixer-oscillator is active and the UHF band is 'OFF'. PVHFL and PVHFH are used to select the VHF sub-bands. FMST is a general purpose port, that can be used to switch an FM sound trap. When it is used, the sum of the collector currents has to be limited to 30 mA.

The synthesizer consists of a divide-by-eight prescaler, a 15-bit programmable divider, a crystal oscillator and its programmable reference divider and a phase/frequency detector combined with a charge-pump which drives the tuning amplifier, including 33 V output.

Depending on the reference divider ratio (512, 640 or 1024), the phase comparator operates at 7.8125 kHz, 6.25 kHz or 3.90625 kHz with a 4 MHz crystal.

The device can be controlled according to the I²C-bus format or 3-wire bus format depending on the voltage applied to pin SW (see Table 2). In the 3-wire bus mode (SW = HIGH), pin LOCK/ADC is the lock output. The LOCK output is LOW when the PLL loop is locked. In the I²C-bus mode (SW = LOW), the lock detector bit FL is set to logic 1 when the loop is locked and is read on the SDA line (Status Byte; SB) during a READ operation in I²C-bus mode only. The Analog-to-Digital Converter (ADC) input is available on pin LOCK/ADC for digital AFC control in the I²C-bus mode only. The ADC code is read during a READ operation on the I²C-bus (see Table 11). In test mode, pin LOCK/ADC is used as a TEST output for f_{REF} and ¹/₂f_{DIV}, in both I²C-bus mode and 3-wire bus mode (see Table 7).

When the automatic charge-pump current switch mode is activated and when the loop is phase-locked, the charge-pump current value is automatically switched to LOW. This action is taken to improve the carrier-to-noise ratio. The status of this feature can be read in the ACPS flag during a READ operation on the I²C-bus (see Table 9).

TDA6402; TDA6402A; TDA6403; TDA6403A

I²C-bus format (SW = GND)

Five serial bytes (including address byte) are required to address the device, select the VCO frequency, program the four ports, set the charge-pump current and set the reference divider ratio. The device has four independent I²C-bus addresses which can be selected by applying a specific voltage on input CE (see Table 6).

3-wire bus format (SW = V_{CC} or OPEN)

Data is transmitted to the devices during a HIGH-level on input CE (enable line). The device is compatible with 18-bit and 19-bit data formats, as shown in Figs 4 and 5. The first four bits are used to program the PNP ports and the remaining bits control the programmable divider. A 27-bit data format may also be used to set the charge-pump current, the reference divider ratio and for test purposes (see Fig.6).

It is not allowed to address the devices with words whose length is different from 18, 19 or 27 bits.

TYPE NUMBER	DATA WORD	REFERENCE DIVIDER ⁽¹⁾	FREQUENCY STEP
TDA6402; TDA6402A; TDA6403; TDA6403A	18-bit	512	62.50 kHz
TDA6402; TDA6402A; TDA6403; TDA6403A	19-bit	1024	31.25 kHz
TDA6402; TDA6402A; TDA6403; TDA6403A	27-bit	programmable	programmable

Table 1 Data word length for 3-wire bus

Note

The selection of the reference divider is given by an automatic identification of the data word length. When the 27-bit format is used, the reference divider is controlled by RSA and RSB bits (see Table 8). More details are given in Chapter "PLL functional description", Section "3-wire bus mode (SW = OPEN or V_{CC})".

ORDERING INFORMATION

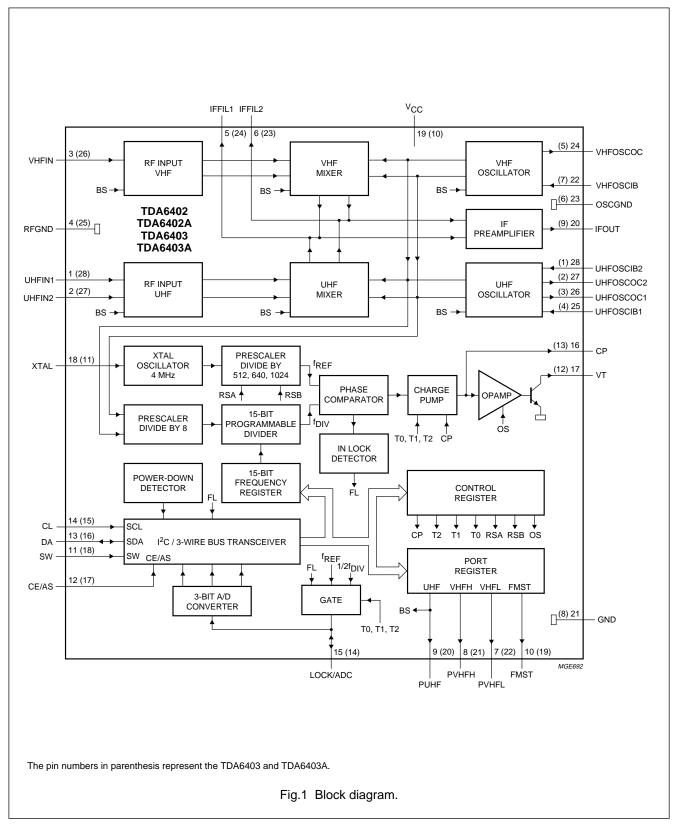
TYPE		PACKAGE	
NUMBER	NAME	DESCRIPTION	VERSION
TDA6402M; TDA6402AM ⁽¹⁾	SSOP28	plastic shrink small outline package; 28 leads; body width 5.3 mm	SOT341-1
TDA6403M; TDA6403AM	SSOP28	plastic shrink small outline package; 28 leads; body width 5.3 mm	SOT341-1

Note

1. The TDA6402AM is available on request.

TDA6402; TDA6402A; TDA6403; TDA6403A

BLOCK DIAGRAM

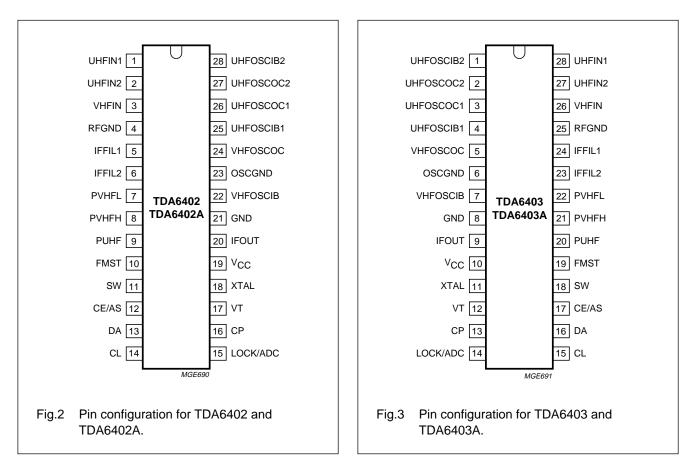


TDA6402; TDA6402A; TDA6403; TDA6403A

PINNING

PIN		IN		
SYMBOL	TDA6402; TDA6402A	TDA6403; TDA6403A	DESCRIPTION	
UHFIN1	1	28	UHF RF input 1	
UHFIN2	2	27	UHF RF input 2	
VHFIN	3	26	VHF RF input	
RFGND	4	25	RF ground	
IFFIL1	5	24	IF filter output 1	
IFFIL2	6	23	IF filter output 2	
PVHFL	7	22	PNP port output, general purpose (e.g. VHF low sub-band)	
PVHFH	8	21	PNP port output, general purpose (e.g. VHF high sub-band)	
PUHF	9	20	PNP port output, UHF band	
FMST	10	19	PNP port output, general purpose (e.g. FM sound trap)	
SW	11	18	bus format selection input (I ² C-bus/3-wire bus)	
CE/AS	12	17	Chip Enable/Address Selection input	
DA	13	16	serial data input/output	
CL	14	15	serial clock input	
LOCK/ADC	15	14	lock detector output (3-wire bus)/ADC input (I ² C-bus)	
СР	16	13	charge pump output	
VT	17	12	tuning voltage output	
XTAL	18	11	crystal oscillator input	
V _{CC}	19	10	supply voltage	
IFOUT	20	9	IF output	
GND	21	8	digital ground	
VHFOSCIB	22	7	VHF oscillator input base	
OSCGND	23	6	oscillator ground	
VHFOSCOC	24	5	VHF oscillator output collector	
UHFOSCIB1	25	4	UHF oscillator input base 1	
UHFOSCOC1	26	3	UHF oscillator output collector 1	
UHFOSCOC2	27	2	UHF oscillator output collector 2	
UHFOSCIB2	28	1	UHF oscillator input base 2	

TDA6402; TDA6402A; TDA6403; TDA6403A



PLL FUNCTIONAL DESCRIPTION

The device is controlled via the I²C-bus or the 3-wire bus, depending on the voltage applied on the SW input. A HIGH level on the SW input enables the 3-wire bus; CE/AS, DA and CL inputs are used as ENABLE (CE), DATA and CLOCK inputs respectively. A LOW level on SW input enables the I²C-bus; the CE/AS, DA and CL inputs are used as address selection (AS), SDA and SCL input respectively (see Table 2).

Table 2 E	Bus format selection	
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	P	IN				
SYMBOL	TDA6402; TDA6402A	TDA6403; TDA6403A	3-WIRE BUS MODE	I ² C-BUS MODE		
SW	11	18	HIGH level or OPEN	LOW level or GND		
CE/AS	12	17	ENABLE input	address selection input		
DA	13	16	DATA input	SDA input		
CL	14	15	CLOCK input	SCL input		
LOCK/ADC	15	14	LOCK/TEST output	ADC input/TEST output		

I²C-bus mode (SW = GND)

WRITE MODE; R/W = 0 (see Tables 3 and 4)

Data bytes can be sent to the device after the address transmission (first byte). Four data bytes are needed to fully program the device. The bus transceiver has an auto-increment facility which permits the programming of the device within one single transmission (address + 4 data bytes).

The device can also be partially programmed providing that the first data byte following the address is divider byte 1 (DB1) or control byte (CB). The bits in the data bytes are defined in Tables 3 and 4. The first bit of the first data byte transmitted indicates whether frequency data (first bit = 0) or control and band-switch data (first bit = 1)

TDA6402; TDA6402A; TDA6403; TDA6403A

will follow. Until an I²C-bus STOP command is sent by the controller, additional data bytes can be entered without the need to re-address the device. The frequency register is loaded after the 8th clock pulse of the second divider byte (DB2), the control register is loaded after the 8th clock pulse of the control byte (CB) and the band-switch register is loaded after the 8th clock pulse of the band switch byte (BB).

I²C-BUS ADDRESS SELECTION

The module address contains programmable address bits (MA1 and MA0) which offer the possibility of having several synthesizers (up to 4) in one system by applying a specific voltage on the CE input. The relationship between MA1 and MA0 and the input voltage applied to the CE input is given in Table 6.

Table 3	I ² C-bus data format,	t, 'write' mode for the TDA6402 and TDA6403	
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NAME	BYTE	BITS								
NAME	BTIC	MSB							LSB	ACK
Address byte	ADB	1	1	0	0	0	MA1	MA0	R/W = 0	А
Divider byte 1	DB1	0	N14	N13	N12	N11	N10	N9	N8	А
Divider byte 2	DB2	N7	N6	N5	N4	N3	N2	N1	N0	А
Control byte	СВ	1	CP	T2	T1	Т0	RSA	RSB	OS	А
Band-switch byte	BB	Х	Х	Х	Х	FMST	PUHF	PVHFH	PVHFL	А

Table 4 I²C-bus data format, 'write' mode for the TDA6402A and TDA6403A

NAME	DVTC	BITS								
NAME	BYTE	MSB							LSB	ACK
Address byte	ADB	1	1	0	0	0	MA1	MA0	R/W = 0	А
Divider byte 1	DB1	0	N14	N13	N12	N11	N10	N9	N8	А
Divider byte 2	DB2	N7	N6	N5	N4	N3	N2	N1	N0	А
Control byte	СВ	1	CP	T2	T1	Т0	RSA	RSB	OS	А
Band-switch byte	BB	Х	Х	Х	Х	PUHF	FMST	PVHFH	PVHFL	А

TDA6402; TDA6402A; TDA6403; TDA6403A

SYMBOL	DESCRIPTION			
A	acknowledge			
MA1, MA0	programmable address bits (see Table 6)			
N14 to N0	programmable divider bits; N = N14 \times 2 ¹⁴ + N13 \times 2 ¹³ + + N1 \times 2 ¹ + N0			
СР	charge pump current:			
	$CP = 0 = 60 \ \mu A$			
	$CP = 1 = 280 \ \mu A$ (default)			
T2, T1, T0	test bits (see Table 7)			
RSA, RSB	reference divider ratio select bits (see Table 8)			
OS	tuning amplifier control bit:			
	OS = 0; normal operation; tuning voltage is 'ON' (default)			
	OS = 1; tuning voltage is 'OFF' (high impedance)			
PVHFL, PVHFH,	PNP ports control bits:			
PUHF, FMST	bit = 0; buffer n is 'OFF' (default)			
	bit = 1; buffer n is 'ON'			
Х	don't care			

Table 6 Address selection (I²C-bus mode)

MA1	MA0	VOLTAGE APPLIED ON CE INPUT (SW = GND)
0	0	0 V to 0.1 \times V _{CC}
0	1	open or 0.2 \times V _{CC} to 0.3 \times V _{CC}
1	0	$0.4 \times V_{CC}$ to $0.6 \times V_{CC}$
1	1	$0.9 \times V_{CC}$ to $1.0 \times V_{CC}$

Table 7 Test modes

T2	T1	то	TEST MODES
0	0	0	automatic charge-pump switched off
0	0	1	automatic charge-pump switched on (note 1)
0	1	Х	charge-pump is 'OFF'
1	1	0	charge-pump is sinking current
1	1	1	charge-pump is sourcing current
1	0	0	f _{REF} is available on pin LOCK/ADC (note 2)
1	0	1	$1/_2 f_{\text{DIV}}$ is available on pin LOCK/ADC (note 2)

Notes

- 1. This is the default mode at power-on reset.
- The ADC input cannot be used when these test modes are active; see Section "Read mode; R/W = 1 (see Table 9)" for more information.

TDA6402; TDA6402A; TDA6403; TDA6403A

RSA	RSB	REFERENCE DIVIDER RATIO
Х	0	640
0	1	1024
1	1	512

Note

1. X = don't care.

READ MODE; R/W = 1 (see Table 9)

Data can be read from the device by setting the R/W bit to 1. After the slave address has been recognized, the device generates an acknowledge pulse and the first data byte (status byte) is transferred on the SDA line (MSB first). Data is valid on the SDA line during a HIGH-level of the SCL clock signal. A second data byte can be read from the device if the microcontroller generates an acknowledge on the SDA line (master acknowledge). End of transmission will occur if no master acknowledge occurs. The device will then release the data line to allow the microcontroller to generate a STOP condition. The POR flag is set to 1 at power-on. The flag is reset when an end-of-data is detected by the device (end of a READ sequence). Control of the loop is made possible with the in-lock flag FL which indicates when the loop is locked (FL = 1).

The automatic charge-pump switch flag (ACPS) is LOW when the automatic charge-pump switch mode is 'ON' and the loop is locked. In other conditions, ACPS = 1. When ACPS = 0, the charge-pump current is forced to the LOW value.

A built-in ADC is available on LOCK/ADC pin (I²C-bus mode only). This converter can be used to apply AFC information to the microcontroller from the IF section of the television. The relationship between the bits A2, A1 and A0 is given in Table 11.

TDA6402; TDA6402A; TDA6403; TDA6403A

NAME	BYTE				B	ITS				АСК
NAME	DIIC	MSB ⁽¹⁾							LSB	ACK
Address byte	ADB	1	1	0	0	0	MA1	MA0	R/W = 1	А
Status byte	SB	POR	FL	ACPS	1	1	A2	A1	A0	-

Note

1. MSB is transmitted first.

Table 10 Description of symbols used in Table 9

SYMBOL	DESCRIPTION
A	acknowledge
POR	power-on reset flag (POR = 1 at power-on)
FL	in-lock flag (FL = 1 when the loop is locked)
ACPS	automatic charge-pump switch flag:
	ACPS = 0; active
	ACPS = 1; not active
A2, A1, A0	digital outputs of the 5-level ADC

Table 11 A to D converter levels (note 1)

A2	A1	A0	VOLTAGE APPLIED ON ADC INPUT
1	0	0	$0.60 \times V_{CC}$ to $1.00 \times V_{CC}$
0	1	1	$0.45 \times V_{CC}$ to $0.60 \times V_{CC}$
0	1	0	$0.30 \times V_{CC}$ to $0.45 \times V_{CC}$
0	0	1	$0.15 \times V_{CC}$ to $0.30 \times V_{CC}$
0	0	0	0 to $0.15 \times V_{CC}$

Note

1. Accuracy is $\pm 0.03 \times V_{CC}.$

POWER-ON RESET

Table 12 Default bits at power-on reset

NAME	BYTE				Bľ	тѕ			
	DIIC	MSB							LSB
Address byte	ADB	1	1	0	0	0	MA1	MA0	Х
Divider byte 1	DB1	0	Х	Х	Х	Х	Х	Х	Х
Divider byte 2	DB2	Х	Х	Х	Х	Х	Х	Х	Х
Control byte	СВ	1	1	0	0	1	Х	1	0
Band switch byte	BB	Х	Х	Х	Х	0	0	0	0

Preliminary specification

5 V mixers/oscillators and synthesizers for cable TV and VCR 2-band tuners

The power-on detection threshold voltage V_{POR} is set to $V_{CC} = 2 V$ at room temperature. Below this threshold, the device is reset to the power-on state.

At power-on state, the charge-pump current is set to 280 μ A, the tuning voltage output is disabled, the test bits T2, T1 and T0 are set to '001' (automatic charge-pump switch 'ON') and RSB is set to 1.

PUHF is 'OFF', which means that the UHF oscillator and the UHF mixer are switched off. Consequently, the VHF oscillator and the VHF mixer are switched on. PVHFL and PVHFH are 'OFF', which means that the VHF tank circuit is working in the VHF I sub-band. The tuning amplifier is switched off until the first transmission. In that case, the tank circuit in VHF I is supplied with the maximum tuning voltage. The oscillator is therefore working at the end of the VHF I sub-band.

3-wire bus mode (SW = OPEN or V_{CC})

During a HIGH-level on the CE input (ENABLE line), the data is clocked into the data register at the HIGH-to-LOW transition of the clock. The first four bits control the PNP ports and are loaded into the internal band switch register on the 5th rising edge of the clock pulse. The frequency bits are loaded into the frequency register at the HIGH-to-LOW transition of the chip enable line when an 18-bit or 19-bit data word is transmitted (see Figs 4 and 5).

When a 27-bit data word is transmitted, the frequency bits are loaded into the frequency register on the 20th rising edge of the clock pulse and the control bits at the HIGH-to-LOW transition of the chip enable line (see Fig.6). In this mode, the reference divider is given by the RSA and RSB bits (see Table 8). The test bits T2, T1 and T0, the charge-pump bit CP, the ratio select bit RSB and the OS bit can only be selected or changed with a 27-bit transmission. They remain programmed if an 18-bit or

TDA6402; TDA6402A; TDA6403; TDA6403A

19-bit transmission occurs. Only RSA is controlled by the transmission length when the 18-bit or 19-bit format is used. When an 18-bit data word is transmitted, the most significant bit of the divider N14 is internally set to 0 and the bit RSA is set to 1. When a 19-bit data word is transmitted, the bit RSA is set to 0.

A data word of less than 18 bits will not affect the frequency register of the device. The definition of the bits is unchanged compared to I^2C -bus mode.

It is not allowed to address the devices with words whose length is different from 18, 19 or 27 bits.

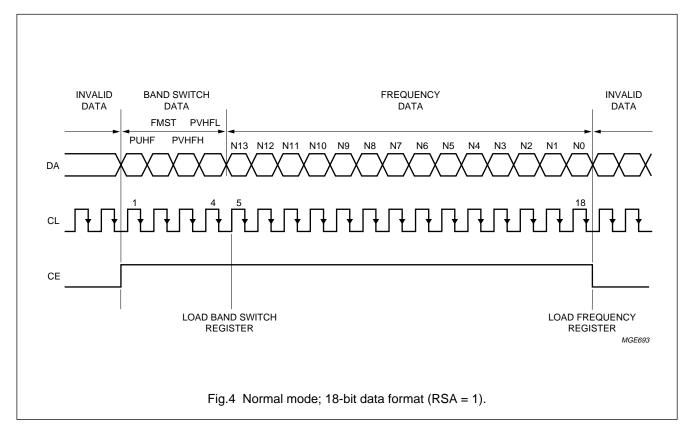
POWER-ON RESET

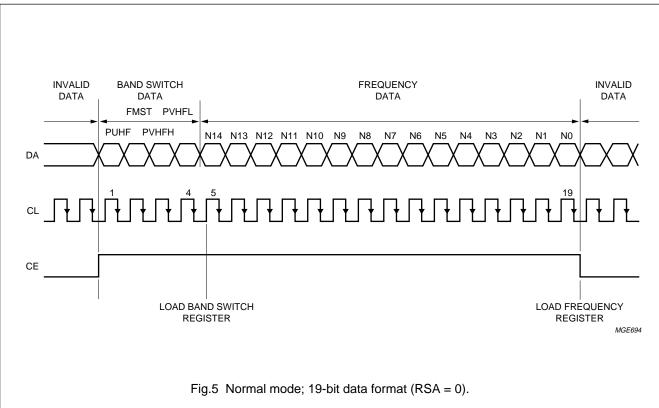
The power-on detection threshold voltage V_{POR} is set to $V_{CC} = 2 V$ at room temperature. Below this threshold, the device is reset to the power-on state.

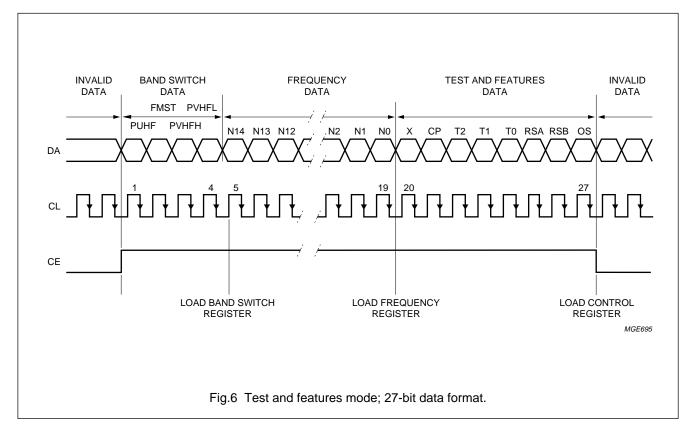
At power-on state, the charge-pump current is set to 280 μ A, the tuning voltage output is disabled, the test bits T2, T1 and T0 are set to '001' (automatic charge-pump switch 'ON') and RSB is set to 1.

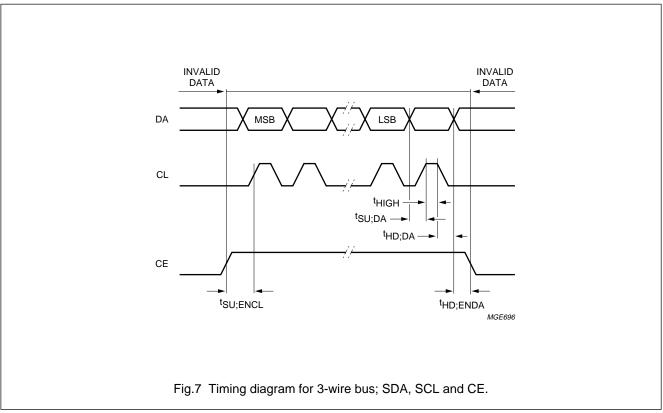
PUHF is 'OFF', which means that the UHF oscillator and the UHF mixer are switched off. Consequently, the VHF oscillator and the VHF mixer are switched on. PVHFL and PVHFH are 'OFF', which means that the VHF tank circuit is working in the VHF I sub-band. The tuning amplifier is switched off until the first transmission. In that case, the tank circuit in VHF I is supplied with the maximum tuning voltage. The oscillator is therefore working at the end of the VHF I sub-band.

If the first sequence transmitted to the device has 18 or 19 bits, the reference divider ratio is set to 512 or 1024, depending on the sequence length. If the sequence has 27 bits, the reference divider ratio is fixed by RSA and RSB bits (see Table 8).

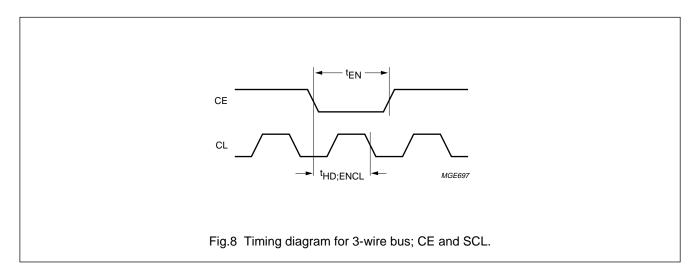








TDA6402; TDA6402A; TDA6403; TDA6403A



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

	Р	IN				
SYMBOL	TDA6402 TDA6402A	TDA6403 TDA6403A	PARAMETER	MIN.	MAX.	UNIT
V _{CC}	19	10	supply voltage	-0.3	+6	V
			operating supply voltage	4.5	5.5	V
V _{BSn}	7 to 10	19 to 22	PNP port output voltage	-0.3	+6	V
I _{BSn}	7 to 10	19 to 22	PNP port output current	-1	+30	mA
V _{CP}	16	13	charge-pump output voltage	-0.3	+6	V
V _{SW}	11	18	bus format selection input voltage	-0.3	+6	V
V _{VT}	17	12	tuning voltage output	-0.3	+35	V
VLOCK/ADC	15	14	LOCK/ADC input/output voltage	-0.3	+6	V
V _{CL}	14	15	serial clock input voltage	-0.3	+6	V
V _{DA}	13	16	serial data input/output voltage	-0.3	+6	V
I _{DA}	13	16	data output current (I ² C-bus mode)	-1	+10	mA
V _{CE}	12	17	chip enable/address selection input voltage	-0.3	+6	V
V _{XTAL}	18	11	crystal input voltage	-0.3	+6	V
lo	1 to 6, 19 to 28	1 to 10, 23 to 28	output current of each pin to ground	_	-10	mA
t _{sc(max)}	-	-	maximum short-circuit time (all pins to V_{CC} and all pins to GND, OSCGND, RFGND)	-	10	S
T _{stg}	-	-	IC storage temperature	-40	+150	°C
T _{amb}	-	-	operating ambient temperature	-10	+85	°C
Tj	-	-	junction temperature	_	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	TYP.	UNIT
R _{th j-a}	thermal resistance from junction to ambient in free air	90	K/W

TDA6402; TDA6402A; TDA6403; TDA6403A

PLL PART CHARACTERISTICS

 V_{CC} = 4.5 to 5.5 V; T_{amb} = –10 to 85 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
PLL part			•	•		
SUPPLY						
V _{CC}	supply voltage		4.5	5.0	5.5	V
I _{CC}	supply current	I _{CC} measured at V _{CC(max)}	_	68	77	mA
		one PNP port is 'ON'; sourcing 25 mA	_	98	110	mA
		one PNP port is 'ON'; sourcing 25 mA and a second one is 'ON'; sourcing 5 mA	-	108	117	mA
FUNCTIONA	L RANGE				•	
V _{POR}	power-on reset supply voltage	supply voltage below which power-on reset is active	1.5	2.0	-	V
T _{amb}	operating ambient temperature		-10	-	+85	°C
N	divider ratio	15-bit frequency word	256	_	32767	
		14-bit frequency word	256	-	16383	
f _{XTAL}	crystal oscillator	R _{XTAL} = 25 to 300 Ω	3.2	4.0	4.48	MHz
Z _{XTAL}	input impedance (absolute value)	f _{XTAL} = 4 MHz	600	1200	-	Ω
PNP PORT	S			•	-	
I _{BSn(off)}	leakage current	V _{CC} = 5.5 V; V _{Pn} = 0 V	-10	-	-	μA
V _{BSn(sat)}	output saturation voltage	one buffer output is 'ON', sourcing 25 mA; $V_{Pn(sat)} = V_{CC} - V_{Pn}$	_	0.25	0.4	V
LOCK OUT	PUT IN 3-WIRE BUS MODE (PNP (COLLECTOR OUT)	1	1	-	I
I _{UNLOCK}	output current when the PLL is out-of-lock	V _{CC} = 5.5 V; V _{OUT} = 5.5 V	-	-	100	μA
V _{UNLOCK}	output saturation voltage when the PLL is out-of-lock	$I_{SOURCE} = 200 \ \mu A;$ $V_{UNLOCK} = V_{CC} - V_{OUT}$	-	0.4	0.8	V
V _{LOCK}	output voltage	the PLL is locked	_	0.01	0.40	V
ADC INPUT	IN I ² C-BUS MODE					•
V _{ADC}	ADC input voltage	see Table 11	0	-	V _{CC}	V
I _{ADCH}	HIGH-level input current	V _{ADC} = V _{CC}	_	_	10	μA
I _{ADCL}	LOW-level input current	V _{ADC} = 0 V	-10	_	-	μA
SW INPUT	(BUS FORMAT SELECTION)					
V _{SWL}	LOW-level input voltage		0	-	1.5	V
V _{SWH}	HIGH-level input voltage		3	-	V _{CC}	V
I _{SWH}	HIGH-level input current	$V_{SW} = V_{CC}$	-	-	10	μA
I _{SWL}	LOW-level input current	$V_{SW} = 0 V$	-100	-	-	μA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
CE/AS INP	UT (CHIP ENABLE/ADDRESS SELE	CTION)	-	l		4
V _{CE/ASL}	LOW-level input voltage		0	_	1.5	V
V _{CE/ASH}	HIGH-level input voltage		3	-	5.5	V
I _{CE/ASH}	HIGH-level input current	V _{CE/AS} = 5.5 V	-	-	10	μA
I _{CE/ASL}	LOW-level input current	$V_{CE/AS} = 0 V$	-10	-	-	μA
CL AND DA	NINPUTS		•			•
V _{CL/DAL}	LOW-level input voltage		0	-	1.5	V
V _{CL/DAH}	HIGH-level input voltage		3	-	5.5	V
I _{CL/DAH}	HIGH-level input current	V _{BUS} = 5.5 V; V _{CC} = 0 V	-	-	10	μA
		$V_{BUS} = 5.5 \text{ V}; V_{CC} = 5.5 \text{ V}$	-	-	10	μA
I _{CL/DAL}	LOW-level input current	V _{BUS} = 1.5 V; V _{CC} = 0 V	-	-	10	μA
		$V_{BUS} = 0 V; V_{CC} = 5.5 V$	-10	_	-	μA
DA OUTPUT	Г (I ² C-BUS MODE)					
I _{DAH}	leakage current	V _{DA} = 5.5 V	-	-	10	μA
V _{DA}	output voltage	I _{DA} = 3 mA (sink current)	-	_	0.4	V
CLOCK FRE	QUENCY				-	-
f _{clk}	clock frequency		_	100	400	kHz
-					_	-
I _{CPH}	HIGH-level input current (absolute value)	CP = 1	-	280	-	μA
I _{CPL}	LOW-level input current (absolute value)	CP = 0	_	60	-	μΑ
V _{CP}	output voltage	PLL is locked; T _{amb} = 25 °C	-	1.95	_	V
V _{CPleak}	off-state leakage current	T2 = 0; T1 = 1	-15	-0.5	+15	nA
TUNING VOI	LTAGE OUTPUT VT		-	•	-	-
I _{VTOFF}	leakage current when switched-off	OS = 1; tuning supply = 33 V	_	-	10	μA
V_{VT}	output voltage when the loop is closed	OS = 0; T2 = 0; T1 = 0; T0 = 1; R _{LOAD} = 22 kΩ; tuning supply = 33 V	0.2	-	32.7	V
3-WIRE BUS	S TIMING			•	-	-
t _{HIGH}	clock HIGH time	see Fig.7	2	_	_	μs
t _{SU;DA}	data set-up time	see Fig.7	2	_	_	μs
t _{HD;DA}	data hold time	see Fig.7	2	-	_	μs
t _{SU;ENCL}	enable to clock set-up time	see Fig.7	10	-	-	μs
t _{HD;ENDA}	enable to data hold time	see Fig.7	2	-	-	μs
t _{EN}	enable time between two transmissions	see Fig.8	10	-	_	μs
t _{HD;ENCL}	enable to clock active edge hold time	see Fig.8	6	-	-	μs

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Mixer/osc	illator part (V _{CC} = 5 V) (measu	red in circuit of Fig.19; unless otherwise	specified)	1	
VHF MIXER	R (INCLUDING IF AMPLIFIER)					
f _{RF}	RF frequency	note 1	55.25	_	361.25	MHz
G _v	voltage gain	f _{RF} = 57.5 MHz; see Fig.12	16.5	19	21.5	dB
		f _{RF} = 357.5 MHz; see Fig.12	16.5	19	21.5	dB
NF	noise figure	f _{RF} = 50 MHz; see Figs 13 and 14	-	8.5	9.5	dB
		f _{RF} = 150 MHz; see Figs 13 and 14	-	8.5	10.5	dB
		f _{RF} = 300 MHz; see Fig.14	-	9.5	12.5	dB
Vo	output voltage causing 1%	f _{RF} = 55.25 MHz; see Fig.15	105	108	_	dBμV
	cross modulation in channel	f _{RF} = 361.25 MHz; see Fig.15	105	108	_	dBμV
Vi	input voltage causing pulling in channel (750 Hz)	f _{RF} = 361.25 MHz; note 2	-	83	-	dBμV
g _{os}	optimum source	f _{RF} = 50 MHz	_	0.7	_	mS
	conductance for noise figure	f _{RF} = 150 MHz	_	0.9	-	mS
		f _{RF} = 300 MHz	_	1.5	_	mS
gi	input conductance	f _{RF} = 55.25 MHz; see Fig.9	_	0.25	_	mS
		f _{RF} = 361.25 MHz; see Fig.9	_	0.5	_	mS
Ci	input capacitance	f _{RF} = 57.5 to 357.5 MHz; see Fig.9	-	1.3	_	pF
VHF oscil	LATOR; see Fig.19					
f _{OSC}	oscillator frequency	note 3	101	_	407	MHz
$\Delta f_{OSC(V)}$	oscillator frequency shift	$\Delta V_{CC} = 5\%$; note 4	_	20	120	kHz
		$\Delta V_{CC} = 10\%$; note 4	_	110	_	kHz
$\Delta f_{OSC(T)}$	oscillator frequency drift	$\Delta T = 25 \ ^{\circ}C$; with compensation; note 5	-	1600	2000	kHz
$\Delta f_{OSC(t)}$	oscillator frequency drift	5 s to 15 min after switch on; note 6	-	600	1100	kHz
Φ_{OSC}	phase noise, carrier to noise sideband	±100 kHz frequency offset; worst case in the frequency range	-	100	-	dBc/Hz
RSC	ripple susceptibility of V _P (peak-to-peak value)	$V_P = 5$ V; worst case in the frequency range; ripple frequency 500 kHz; note 7	15	20	_	mV
UHF MIXER	R (INCLUDING IF AMPLIFIER)					
f _{RF}	RF frequency	note 1	367.25	_	801.25	MHz
Gv	voltage gain	f _{RF} = 369.5 MHz; see Fig.16	26	29	32	dB
		f _{RF} = 803.5 MHz; see Fig.16	26	29	32	dB
NF	noise figure	f _{RF} = 369.5 MHz; see Fig.17	-	9	11	dB
	(not corrected for image)	f _{RF} = 803.5 MHz; see Fig.17	_	10	12	dB
Vo	output voltage causing 1%	f _{RF} = 367.25 MHz; see Fig.18	105	108	_	dBμV
	cross modulation in channel	f _{RF} = 801.25 MHz; see Fig.18	105	108	_	dBμV
Vi	input voltage causing pulling in channel (750 Hz)	f _{RF} = 801.25 MHz; note 2	-	82	-	dBµV

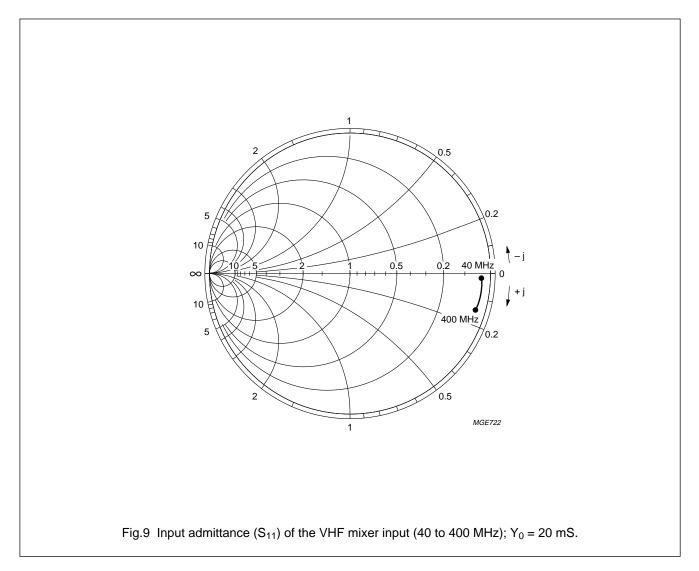
TDA6402; TDA6402A; TDA6403; TDA6403A

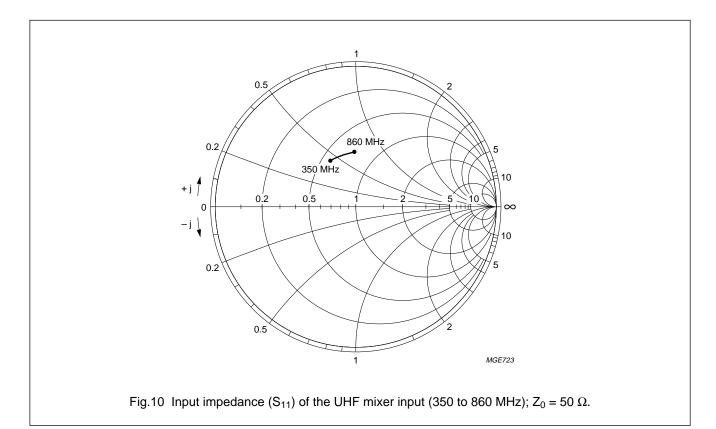
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zi	input impedance ($R_S + jL_S\omega$)	R _S at f _{RF} = 367.25 MHz; see Fig.10	_	30	-	Ω
		R _S at f _{RF} = 801.25 MHz; see Fig.10	_	38	-	Ω
		L _S at f _{RF} = 367.25 MHz; see Fig.10	_	9	-	nH
		L _S at f _{RF} = 801.25 MHz; see Fig.10	-	6	-	nH
UHF OSCIL	LATOR			·		
f _{OSC}	oscillator frequency	note 3	413	-	847	MHz
$\Delta f_{OSC(V)}$	oscillator frequency shift	$\Delta V_{CC} = 5\%$; note 4	-	10	80	kHz
		$\Delta V_{CC} = 10\%$; note 4	-	300	-	kHz
$\Delta f_{OSC(T)}$	oscillator frequency drift	$\Delta T = 25 \ ^{\circ}C$; with compensation; note 5	_	2000	2700	kHz
$\Delta f_{OSC(t)}$	oscillator frequency drift	5 s to 15 min after switching on; note 6	-	300	1300	kHz
Φ_{OSC}	phase noise, carrier to noise sideband	\pm 100 kHz frequency offset; worst case in the frequency range	-	100	-	dBc/Hz
RSC	ripple susceptibility of V _P (peak-to-peak value)	$V_P = 5 V$ (worst case in the frequency range); ripple frequency 500 kHz; note 7	15	28	-	mV
IF AMPLIFIE	R					
S ₂₂	output reflection coefficient	magnitude; see Fig.11	-	-13.1	-	dB
		phase; see Fig.11	_	2.9	-	0
Zo	output impedance	R _S at 43.5 MHz; see Fig.11	-	75	-	Ω
	$(R_{S} + jL_{S}\omega)$	L _S at 43.5 MHz; see Fig.11	_	6.6	-	nH
REJECTION	AT THE IF OUTPUT					
INT _{DIF} level of divider interferences not in the IF signal		note 8; worst case: channel C	_	25	-	dBμV
INTR _{XTAL}	crystal oscillator interferences rejection	V_{IF} = 100 dBµV; worst case in the frequency range; note 9	60	-	-	dBc
INTRF _{REF}	reference frequency rejection	V_{IF} = 100 dBµV; worst case in the frequency range; note 10		-	-	dBc
INT _{CH6}	channel 6 beat	$V_{RFpix} = V_{RFsnd} = 80 \text{ dB}\mu\text{V}$; note 11	57	-	-	dBc
INT _{CHA-5}	channel A-5 beat	V _{RFpix} = 80 dBμV; note 12	60	-	-	dBc

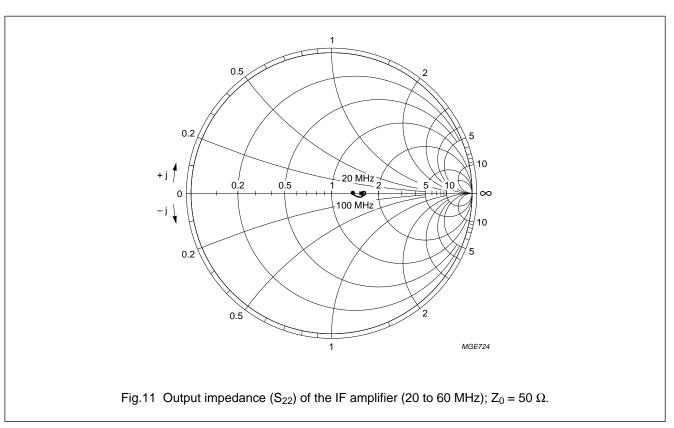
Notes

- 1. The RF frequency range is defined by the oscillator frequency range and the intermediate frequency (IF).
- 2. This is the level of the RF signal (100% amplitude modulated with 11.89 kHz) that causes a 750 Hz frequency deviation on the oscillator signal; it produces sidebands 30 dB below the level of the oscillator signal.
- 3. Limits are related to the tank circuits used in Fig.19; frequency bands may be adjusted by the choice of external components.
- The frequency shift is defined as a change in oscillator frequency when the supply voltage varies from V_{CC} = 5 to 4.75 V (4.5 V) or from V_{CC} = 5 to 5.25 V (5.5 V). The oscillator is free running during this measurement.
- 5. The frequency drift is defined as a change in oscillator frequency when the ambient temperature varies from $T_{amb} = 25$ to 50 °C or from $T_{amb} = 25$ to 0 °C. The oscillator is free running during this measurement.
- 6. Switch-on drift is defined as the change in oscillator frequency between 5 s and 15 min after switch on. The oscillator is free running during this measurement.

- The ripple susceptibility is measured for a 500 kHz ripple at the IF output using the measurement circuit of Fig.19; the level of the ripple signal is increased until a difference of 53.5 dB occurs between the IF carrier fixed at 100 dBμV and the sideband components.
- 8. This is the level of divider interferences close to the IF frequency. For example channel C: f_{OSC} = 179 MHz, 1/4 f_{OSC} = 44.75 MHz. Divider interference is measured with the Philips 37511 demonstration board in accordance with Fig.19. All ground pins are connected to a single ground plane under the IC. The VHFIN input must be left open (i.e. not connected to any load or cable); The UHFIN1 and UHFIN2 inputs are connected to a hybrid. The measured levels of divider interference are influenced by layout, grounding and port decoupling. The measurement results could vary by as much as 10 dB with respect to the specification.
- 9. Crystal oscillator interference means the 4 MHz sidebands caused by the crystal oscillator. The rejection has to be greater than 60 dB for an IF output signal of 100 dBμV.
- 10. The reference frequency rejection is the level of reference frequency sidebands related to the sound sub-carrier. The rejection has to be greater than 50 dB for an IF output signal of 100 dBμV.
- 11. Channel 6 beat is the interfering product of $f_{RFpix} + f_{RFsnd} f_{OSC}$ of channel 6 at 42 MHz.
- 12. Channel A-5 beat is the interfering product of f_{RFpix} , f_{IF} and f_{OSC} of channel A-5; f_{BEAT} = 45.5 MHz. The possible mechanisms are: $f_{OSC} 2 \times f_{IF}$ or $2 \times f_{RFpix} f_{OSC}$. For the measurement V_{RF} = 80 dBµV.

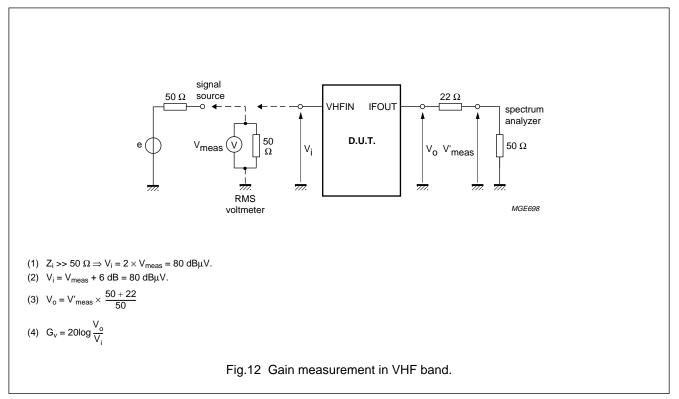


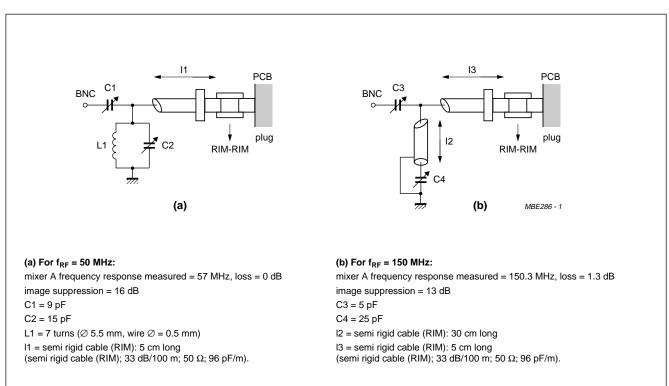




TDA6402; TDA6402A; TDA6403; TDA6403A

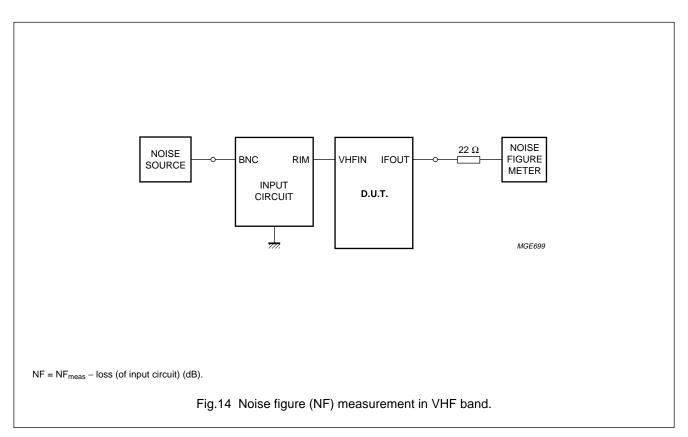
TEST AND APPLICATION INFORMATION

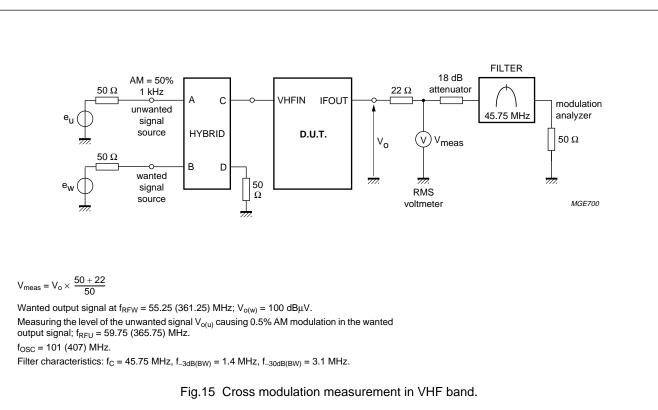


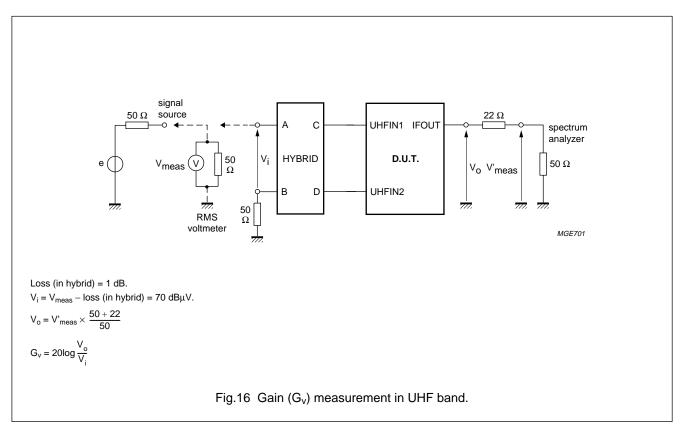


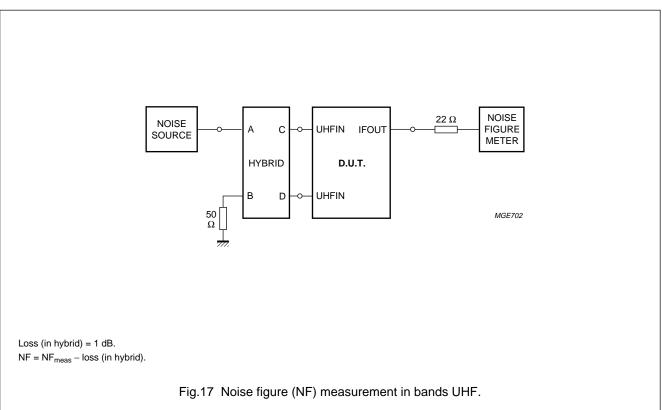
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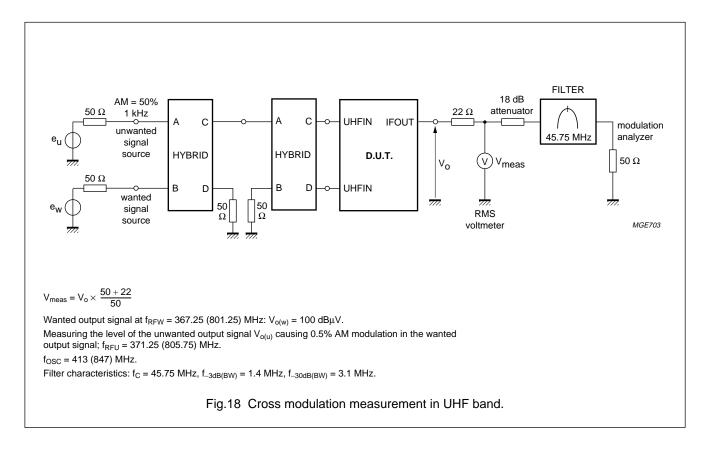
Fig.13 Input circuit for optimum noise figure in VHF band.

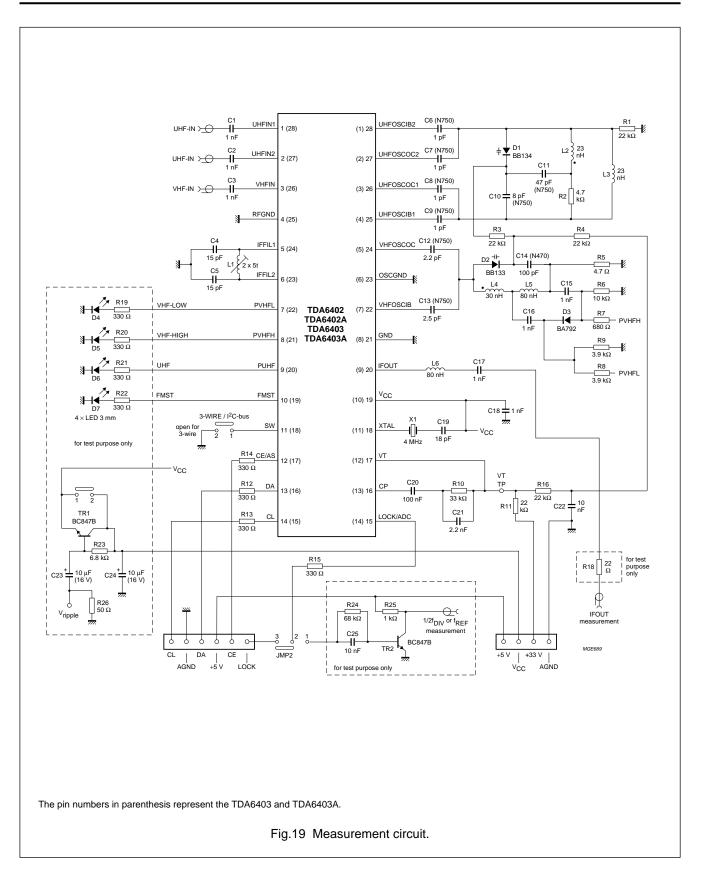












TDA6402; TDA6402A; TDA6403; TDA6403A

Component values for measurement circuit

Table 13 Capacitors (all SMD and NP0)

COMPONENT	VALUE				
C1	1 nF				
C2	1 nF				
C3	1 nF				
C4	15 pF				
C5	15 pF				
C6	1 pF (N750)				
C7	1 pF (N750)				
C8	1 pF (N750)				
C9	1 pF (N750)				
C10	8 pF (N750)				
C11	47 pF (N750)				
C12	2.2 pF (N750)				
C13	2.7 pF (N750)				
C14	100 pF (N470)				
C15	1 nF				
C16	1 nF				
C17	1 nF				
C18	1 nF				
C19	18 pF				
C20	100 nF				
C21	2.2 nF				
C22	10 nF				
C23	10 µF (16 V; electrolytic)				
C24	10 µF (16 V; electrolytic)				
C25	10 nF				

Table 14 Resistors (all SMD)

COMPONENT	VALUE				
R1	22 kΩ				
R2	4.7 kΩ				
R3	22 kΩ				
R4	22 kΩ				
R5	4.7 Ω				
R6	10 kΩ				
R7	680 Ω				
R8	3.9 kΩ				
R9	3.9 kΩ				
R10	33 kΩ				

COMPONENT	VALUE
R11	22 kΩ
R12	330 Ω
R13	330 Ω
R14	330 Ω
R15	330 Ω
R16	22 kΩ
R18	22 Ω
R19	330 Ω
R20	330 Ω
R21	330 Ω
R22	330 Ω
R23	6.8 kΩ
R24	68 kΩ
R25	1 kΩ
R26	50 Ω

Table 15 Diodes and ICs

COMPONENT	VALUE
D1	BB134
D2	BB133
D3	BA792
IC	TDA6402; TDA6402A;
	TDA6403; TDA6403A

Table 16 Coils (wire size 0.4 mm)

COMPONENT	VALUE
L2	23 nH
L3	23 nH
L4	30 nH
L5	80 nH
L6	80 nH

Table 17 Transformer (note 1)

COMPONENT	VALUE
L1	2×5 turns

Note

1. Coil type: TOKO 7kN; material: 113 kN; screw core: 03-0093; pot core: 04-0026.

TDA6402; TDA6402A; TDA6403; TDA6403A

Table 18	Crystal
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COMPONENT	VALUE				
X1	4 MHz				

Table [•]	19	Transistors
IGNIC		nunoiotoro

COMPONENT	VALUE
TR1	BC847B
TR2	BC847B

Tuning amplifier

The tuning amplifier is capable of driving the varicap voltage without an external transistor. The tuning voltage output must be connected to an external load of 27 k Ω which is connected to the tuning voltage supply rail. The loop filter design depends on the oscillator characteristics and the selected reference frequency.

Crystal oscillator

The crystal oscillator uses a 4 MHz crystal connected in series with an 18 pF capacitor thereby operating in the series resonance mode. Connecting the oscillator to the supply voltage is preferred, but it can also be connected to ground.

Examples of I²C-bus sequences (SW = V_{CC}) for TDA6402 and TDA6403

Tables 20 to 24 show the various sequences where:

 $f_{OSC} = 100 \text{ MHz}$ PVHFL = 'ON' to switch on VHF I FMST is 'ON' to switch on an FM sound trap $I_{CP} = 280 \mu A$ N = 512 $f_{XTAL} = 4 \text{ MHz}$ S = START A = acknowledgeP = STOP.

For the complete sequence see Table 20 (sequence 1) or Table 21 (sequence 2).

Table 20 Complete sequence 1

START		RESS TE	DIVI BY1	DER FE 1	DIVI BY1	DER TE 2	CON BY	-	BAND S BY	SWITCH TE	STOP
S	C2	А	06	Α	40	A	CE	А	09	A	Р

Table 21 Complete sequence 2

START		RESS TE	CON BY	TROL TE	BAND S BY	SWITCH TE	DIVI BY		DIVI BY1		STOP
S	C2	A	CE	A	09	A	06	A	40	A	Р

Table 22 Divider bytes only sequence

S C	2 A	06	А	40	А	Р
-----	-----	----	---	----	---	---

Р	S	C2	A	CE	A	Р

Table 23 Control and band switch bytes only sequence

S	C2	А	CE	А	09	А	Р
---	----	---	----	---	----	---	---

TDA6402; TDA6402A; TDA6403; TDA6403A

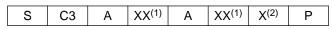
Table 25 Status byte acquisition

	-		(4)	(0)	_
S	C3	A	XX ⁽¹⁾	X ⁽²⁾	Р

Notes

- 1. XX = Read status byte.
- X = No acknowledge from the master means end of sequence.

Table 26 Two status bytes acquisition



Notes

- 1. XX = Read status byte.
- 2. X = No acknowledge from the master means end of sequence.

Other I²C-bus addresses may be selected by applying an appropriate voltage to the CE input.

Examples of 3-wire bus sequences (SW = OPEN)

Table 27 18-bit sequence (f_{OSC} = 800 MHz; PUHF = ON)

1	0	0	0	1	1	0	0	1	0	0	0	0	0	0	0	0	0

The reference divider is automatically set to 512 assuming that RSB has been set to logic 1 at power-on. If RSB has been set to logic 0, in a previous 27-bit sequence, the reference divider will still be set at 640. In that event, the 18-bit sequence has to be adapted to the 640 divider ratio.

Table 28 19-bit sequence (f_{OSC} = 650 MHz; PUHF = ON)

_																			
	1	0	0	0	0	1	0	1	0	0	0	1	0	1	0	0	0	0	0

The reference divider is automatically set to 512 assuming that RSB has been set to logic 1 at power-on. If RSB has been set to logic 0 in a previous 27-bit sequence, the reference divider will still be set at 640. In that event, the 19-bit sequence has to be adapted to the 640 divider ratio.

Table 29 27-bit sequence (f_{OSC} = 750 MHz; PUHF = ON; N = 640; I_{CP} = 60 μ A; no test function)

1 0 0 0 0 1 1 1 1 0 1 0 1 0 1 1 0 1 0 0 1 1 0 1 0	_				_																							
		1	0	0	0	0	1	1	1	0	1	0	1	0	0	1	1	0	0	0	1	0	0	0	1	0	0	0

Table 30 19-bit sequence

			-	-		-					-			-		-	-	
1	0	0	0	0	1	0	1	1	1	0	1	1	1	0	0	0	0	0

This sequence will program f_{OSC} to 600 MHz in 50 kHz steps; I_{CP} remains at 60 μ A.

Table 31 18-bit sequence

1	0	0	0	1	0	1	1	1	0	1	1	1	0	0	0	0	0

This sequence will program f_{OSC} to 600 MHz in 50 kHz steps; I_{CP} remains at 60 μ A.

TDA6402; TDA6402A; TDA6403; TDA6403A

INTERNAL PIN CONFIGURATION

SYMBOL	Р	IN	DESCRIPTION ⁽¹⁾		DC VOLTAGE (V) ⁽²⁾ ed in Fig.19)
	TDA6402; TDA6402A	TDA6403; TDA6403A		VHF	UHF
UHFIN1	1	28		n.a.	1.0
UHFIN2	2	27	(28) (28) (27) MGE704	n.a.	1.0
VHFIN	3	26	(3) (26) (26) (26) (26) (3) (26) (3) (26) (3) (26) (3) (26) (3) (3) (3) (3) (3) (3) (3) (3) (3) (3	1.8	n.a.
RFGND	4	25	(4) MGE706	0.0	0.0
IFFIL1	5	24		3.6	3.6
IFFIL2	6	23	(24) (5) (6) (23) (24) (5) (6) (23) (1) (1) (1) (1) (1) (1) (1) (1) (1) (1)	3.6	3.6

SYMBOL	PIN		DESCRIPTION ⁽¹⁾	AVERAGE DC VOLTAGE (V) ⁽²⁾ (measured in Fig.19)	
	TDA6402; TDA6402A	TDA6403; TDA6403A		VHF	UHF
PVHFL	7	22		0.0 or (V _{CC} – V _{CE})	0.0
PVHFH	8	21		(V _{CC} – V _{CE}) or 0.0	0.0
PUHF	9	20	(22) (21)	0.0	$(V_{CC} - V_{CE})$
FMST	10	19	(20) (20) (20) (10) (19) MGE708	0.0 or (V _{CC} – V _{CE})	0.0
SW	11	18	(1) (18) MGE709	5.0	5.0
CE/AS	12	17	(12) (17) MGE710	1.25	1.25
DA	13	16	(13) (16) MGE711	n.a.	n.a.

SYMBOL	PIN		DESCRIPTION ⁽¹⁾	AVERAGE DC VOLTAGE (V) ⁽²⁾ (measured in Fig.19)	
	TDA6402; TDA6402A	TDA6403; TDA6403A		VHF	UHF
CL	14	15	(14) (15) MGE712	n.a.	n.a.
LOCK/ADC	15	14	(14) (14) <i>MGE713</i>	4.6	4.6
CP	16	13	(13) MGE714	1.9	1.9
VT	17	12	(12) (12) MGE715	V _{VT}	V _{VT}

SYMBOL	PIN		DESCRIPTION ⁽¹⁾		AVERAGE DC VOLTAGE (V) ⁽²⁾ (measured in Fig.19)	
	TDA6402; TDA6402A	TDA6403; TDA6403A		VHF	UHF	
XTAL	18	11	(11) MGE716	3.4	3.4	
V _{cc}	19	10	supply voltage	5.0	5.0	
IFOUT	20	9	(9) MGE717	2.1	2.1	
GND	21	8	(8) MGE718	0.0	0.0	
OSCGND	23	6	(6) MGE719	0.0	0.0	

TDA6402; TDA6402A; TDA6403; TDA6403A

SYMBOL	PIN		DESCRIPTION ⁽¹⁾	AVERAGE DC VOLTAGE (V) ⁽²⁾ (measured in Fig.19)	
	TDA6402; TDA6402A	TDA6403; TDA6403A		VHF	UHF
VHFOSCIB	22	7		1.8	n.a.
VHFOSCOC	24	5	(22) (7) (7) (7) (5) (5) (5) (5) (5) (5) (5) (5) (5) (5	3.0	n.a.
UHFOSCIB1	25	4		n.a.	1.9
UHFOSCOC 1	26	3		n.a.	2.9
UHFOSCOC 2	27	2		n.a.	2.9
UHFOSCIB2	28	1	(4) (4) (1) (1) (1) (1) (1) (1)	n.a.	1.9

Notes

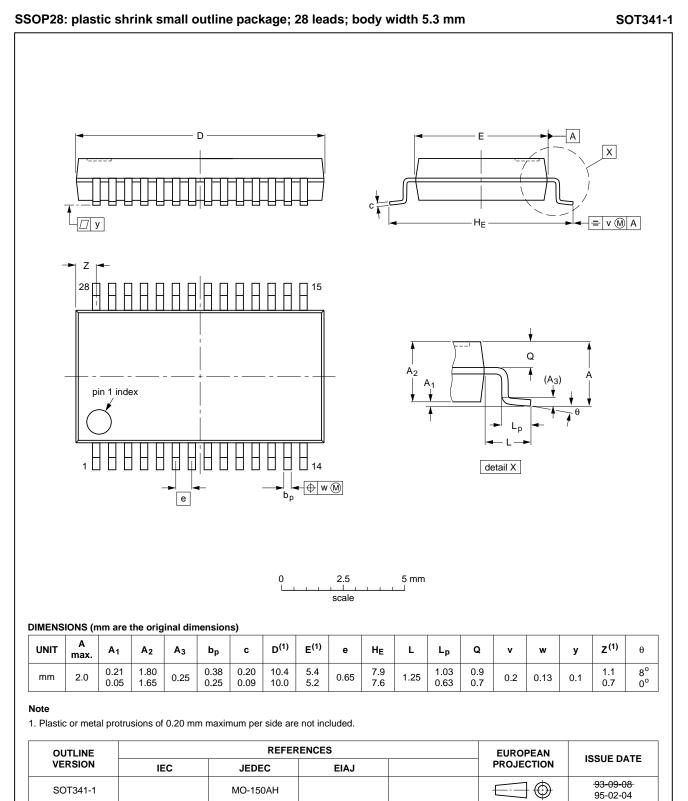
1. The pin numbers in parenthesis represent the TDA6403 and TDA6403A.

2. n.a. = not applicable.

TDA6402; TDA6402A; TDA6403; TDA6403A

5 V mixers/oscillators and synthesizers for cable TV and VCR 2-band tuners

PACKAGE OUTLINE



TDA6402; TDA6402A; TDA6403; TDA6403A

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all SSOP packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

Wave soldering

Wave soldering is **not** recommended for SSOP packages. This is because of the likelihood of solder bridging due to closely-spaced leads and the possibility of incomplete solder penetration in multi-lead devices. If wave soldering cannot be avoided, the following conditions must be observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow and must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

TDA6402; TDA6402A; TDA6403; TDA6403A

DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	roduct specification This data sheet contains final product specifications.			
Limiting values				
more of the limiting values r of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or nay cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification imiting values for extended periods may affect device reliability.			
Application information				

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

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